



24  
ABSTRACT

METHOD OF MANUFACTURING INVERSION TYPE

ICs AND IC MODULE USING SAME

A method of manufacturing inversion type ICs includes connecting a first electrode pad group 22a of a semiconductor chip 21 to an opposite lead group 34b via wires 33; connecting a second electrode pad group 22b to a further lead group 34a via wires; sealing the semiconductor chip, the first and second lead groups and the wires by a resin so that the outer lead portions of the leads are exposed; and bending the outer lead portions of the leads towards the bottom surface of the semiconductor chip. An IC module includes: a mounting substrate 28; a standard type IC 20; an inversion type IC 30 which is mounted on the bottom surface of the mounting substrate so that the leads having the same function as those of the standard type IC come to the same point with the mounting substrate in between, first and second electrode pad groups 22a, 22b formed on the surface of the semiconductor chip being connected via wires to second and first lead groups 34b, 34a, respectively, and the outer lead portions of the leads being bent towards the bottom surface of the semiconductor chip; and a plurality of connecting members, provided on the mounting substrate, for electrically connecting the leads of the standard type IC and the leads of the inversion type IC having the same function as those of the standard type IC.

Figure 1